FUSION TEM



Fusion TEM 200



Fusion TEM 350 / 500

SPECIFICATIONS

	Manufacturer Approved	JEOL, Thermo Fisher Scientific					
General	Compatibility	-	EDS; EELS; STEM; Diffraction Patterns; ETEM; Electron Holography; Raman Spectroscopy				
	Holders	TEM / SEM All devices interchangeable					
	Maximum Resolution	0.6 Å					
	Alpha Tilt	Up to ± 55° (varies by manufacturer and pole piece)					
	Beta Tilt (Double Tilt available)	±10°					
Thermal	Temperature Accuracy	< 5%					
	Temperature Stability	< 0.01 °C					
	Temperature Uniformity	> 99.5% across the entire imaging area					
	Temperature Control	Closed loop temperature compensation					
		Silicon Nitride ~40 nm thick					
	E-chip Coatings	Holey Carbon	~18 nm thick				
		None	N/A				
	Heating/Cooling Rate	Any rate up to 1000 °C/ms					
	Maximum Temperature	1200 °C					
	Low Displacement	7 nm after 5 seconds (325 °C ΔT)					
	Ultimate Drift Rate	< 0.5 nm/min					
cal	Maximum Current	± 100 mA, inquire for higher currents					
	Maximum Voltage	55 V, inquire for voltages up to 200 V					
	Maximum Electric Field	Up to 100 kV/cm					
	AC	Low Frequency					
	Number of E-chip Configurations	30					
tri	Source		Fusion 350		Fusion 500		
Electrothermal Electrical			Current	Voltage	Current	Voltage	
		Accuracy	± 0.15% + 100 nA	± 0.08% + 500 μV	± 0.15% + 2 pA	± 0.02% + 375 μV	
		Resolution	10 pA	50 μV	20 fA	5 μV	
	Measure		Current	Voltage	Current	Voltage	
		Accuracy	± 0.15% + 100 nA	± 0.05% + 400 µV	± 0.15% + 750 fA	± 0.015% + 225 µV	
		Resolution	500 fA	500 μV	100 aA	100 nV	
	Temperature Accuracy	< 5%					
	Temperature Stability	< 0.01 °C					
	Temperature Uniformity	> 99.5% across the entire imaging area					
	Temperature Control	Closed loop					
	Heating/Cooling Rate	Any rate up to	Any rate up to 1000 °C/ms				
	Maximum Temperature	900 ℃					

Specifications are dependent on electron microscope and sample.

